

### 1.5A Ultra-small Load Switch with Slew Rate Control

### **FEATURES**

Integrated P-channel MOSFET load switch

Input voltage: 1.2V to 5.5V

1.5A maximum continuous switch current

Switch on-resistance(typ.):

Rdson=52mΩ at VIN=5.5V

Rdson=58mΩ at VIN=4.2V

Rdson= $66m\Omega$  at VIN=3.3V

Rdson= $80m\Omega$  at VIN=2.5V

Rdson=110m $\Omega$  at VIN=1.8V

Rdson=222mΩ at VIN=1.2V

Controlled slew rate to limit inrush currents

Internal EN Pull-Down Resistor on AW35122

Quick output discharge

• FCDFN 1mm×1mm×0.55mm-4L package

# APPLICATIONS

- Smartphones and Tablets
- Portable Devices
- Wearables

### **GENERAL DESCRIPTION**

The AW3512/AW35122 is a load switch with output slew rate control. The device integrates a  $66m\Omega$  (typ.) P-channel MOSFET, which can operate over a wide input range of 1.2V to 5.5V.

The AW3512/AW35122 features output slew rate control, limiting inrush currents during turn-on to protect downstream devices.

### **DEVICE COMPARISON TABLE**

Part Number	AW3512	AW35122		
Top Mark	SV	UJ		
EN Pull Down Resistor	NO	7.1ΜΩ		

### TYPICAL APPLICATION CIRCUITS

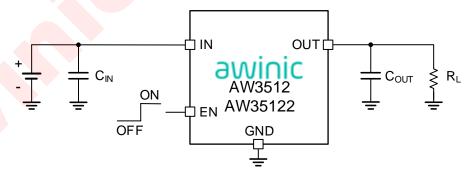


Figure 1 Typical Application circuit of AW3512/AW35122

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# PIN CONFIGURATION AND TOP MARK

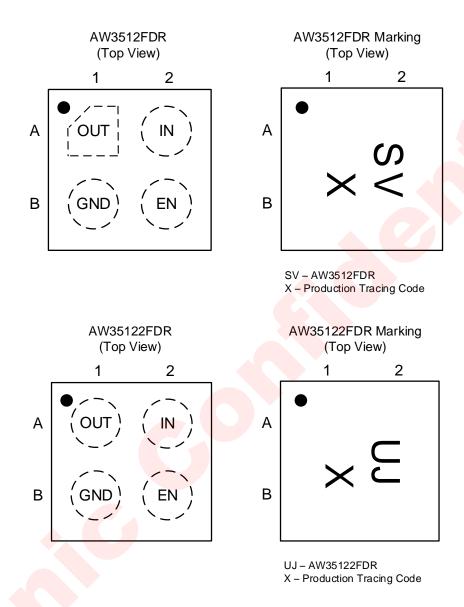


Figure 2 Pin Configuration and Top Mark

# **PIN DEFINITION**

Pin	Name	Description
A1	OUT	Switch output
A2	IN	Switch input and power supply
B1	GND	Device ground
B2	EN	Switch control input, active high, do not leave floating. AW3512.
B2	EN	Switch control input, active high, internal 7.1M $\Omega$ pull down resistor. AW35122



### **FUNCTIONAL BLOCK DIAGRAM**

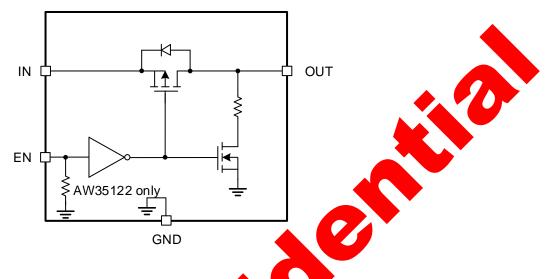
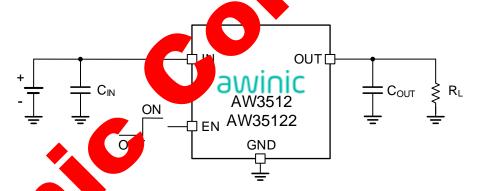


Figure 3 Functional Block Digram

# **TYPICAL APPLICATION CIRCUITS**



Typical Application circuit of AW3512/AW35122

# ORIGING INFORMATION

Number	Number Temperature Packa		Marking	Moisture Sensitivity Level	Environmental Information	Delivery Form
AW3512FDR	-40°C∼85°C	FCDFN 1mm×1mm -4L	SV	MSL1	ROHS+HF	3000 units/ Tape and Reel
AW35122FDR	-40°C∼85°C	FCDFN 1mm×1mm -4L	UJ	MSL1	ROHS+HF	3000 units/ Tape and Reel



# **ABSOLUTE MAXIMUM RATINGS**(NOTE1)

PARAMETER	RANGE		
Supply Voltage Rai	-0.3V to 6V		
Input Voltage Range	EN	-0.3V to 6V	
Output Voltage Range	OUT	-0.3V to 6V	
Maximum Continuous Switch Curre	ent for VIN ≥ 2V <sup>(NOTE 2)</sup>	1.5A	
Maximum Peak Switch Current for	or VIN $\geq 2.5V^{(NOTE 3)}$	2A	
Junction-to-ambient Thermal R	esistance θ <sub>JA</sub> (NOTE 4)	166°C/W	
Operating Free-air Tempe	rature Range	-40°C to 85°C	
Maximum Junction Temp	150°C		
Storage Temperatu	-65°C to 150°C		
Lead Temperature (Solderin	260°C		
	ESD		
HBM (Human Body Mo	odel) (NOTE 5)	±2kV	
CDM(Charged Device N	±1.5kV		
MM(Machine Model	±200V		
Latch-Up (NOTE	+IT : 200mA		
Later-op		-IT:-200mA	

NOTE1: Conditions out of those ranges <u>listed in "absolute maximum ratings"</u> may cause permanent damages to the device. In spite of the limits above, functional operation conditions of the device should within the ranges listed in "recommended operating conditions". Exposure to absolute-maximum-rated conditions for prolonged periods may affect device reliability.

NOTE2: Limited by thermal design.

NOTE3: Limited by thermal design, and tested in 10ms width pulse current.

NOTE4: Thermal resistance from junction to ambient is highly dependent on PCB layout.

NOTE5: The human body model is a 100pF capacitor discharged through a 1.5k $\Omega$  resistor into each pin. Test method: ESDA/JEDEC JS-001-2017.

NOTE6: All pins. Test Condition: ESDA/JEDEC JS-002-2014.

NOTE7: All pins. Test Condition: JESD22-A115C.

NOTE8: Test Condition: JESD78E.

### RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min.	Тур.	Max.	Unit
VIN	Input Voltage	1.2		5.5	V
V <sub>EN</sub>	EN Voltage	0		5.5	V
Vout	Output Voltage	0		Vin	V
Cin	Input capacitance	0.1	1		μF
Соит	Output load capacitance	0.1	1		μF



### **ELECTRICAL CHARACTERISTICS**

 $T_A = -40$ °C to 85°C unless otherwise noted. Typical values are guaranteed for  $V_{IN} = 5V$ ,  $C_{IN} = 1\mu F$ ,  $I_{IN} \le 1.5A$  and  $T_A = 25$ °C.

PA	RAMETER	TEST CONDITION		MIN	TYP	MAX	UNIT
INPUT (	CURRENTS						
		V <sub>IN</sub> =3.3V, V <sub>EN</sub> =3.3V,I <sub>OUT</sub> =0A, T <sub>A</sub> :	=25°C		2	12	nA
	Input quiescent	V <sub>IN</sub> =3.3V, V <sub>EN</sub> =3.3V,I <sub>OUT</sub> =0A, T <sub>A</sub> =	=85°C		9		nA
lQ	current	V <sub>IN</sub> =5.5V, V <sub>EN</sub> =5.5V,I <sub>OUT</sub> =0A, T <sub>A</sub> =	=25°C		15	25	nA
		VIN=5.5V, VEN=5.5V, IOUT=0A, TA	=85°C		10		nA
		V <sub>IN</sub> =1.2V, V <sub>EN</sub> =0V, T <sub>A</sub> =25°C			2		nA
		V <sub>IN</sub> =1.8V, V <sub>EN</sub> =0V, T <sub>A</sub> =25°C			2		nA
		V <sub>IN</sub> =3.3V, V <sub>EN</sub> =0V, T <sub>A</sub> =25°C			6	44	nA
	Shutdown	V <sub>IN</sub> =4.0V, V <sub>EN</sub> =0V, T <sub>A</sub> =25°C			16		nA
I <sub>SD</sub>	current from IN	V <sub>IN</sub> =4.5V, V <sub>EN</sub> =0V, T <sub>A</sub> =25°C			28		nA
	to GND	VIN=5.0V, VEN=0V, TA=25°C			60	970	nA
		VIN=5.0V, VEN=0V, TA=55°C		90		nA	
		V <sub>IN</sub> =5.0V, V <sub>EN</sub> =0V, T <sub>A</sub> =85°C		350		nA	
		V <sub>IN</sub> =5.5V, V <sub>EN</sub> =0V, T <sub>A</sub> =25°C			139		nA
	EN pin leakage current	\\0\\ \\-0\\	AW3512			0.5	μΑ
ILEAKEN		V <sub>IN</sub> =0V, V <sub>EN</sub> =5.0V	AW35122			1.5	μА
Ren	EN pin pull down resistor	V <sub>EN</sub> =5.0V, only for AW35122			7.1		ΜΩ
POWER	SWITCH			l	•		
		VIN=5.5V, VEN=high, IOUT=200mA	, T <sub>A</sub> =25°C		52		
		V <sub>IN</sub> =4.2V, V <sub>EN</sub> =high, I <sub>OUT</sub> =200mA, T <sub>A</sub> =25°C			58		mΩ
Б	Internal switch MOSFET on-	V <sub>IN</sub> =3.3V, V <sub>EN</sub> =high, I <sub>OUT</sub> =200mA, T <sub>A</sub> =25°C			66		
R <sub>dson</sub>	state resistance	V <sub>IN</sub> =3.0V, V <sub>EN</sub> =high, I <sub>OUT</sub> =200mA, T <sub>A</sub> =25°C			70	120	
		V <sub>IN</sub> =1.8V, V <sub>EN</sub> =high, I <sub>OUT</sub> =200mA, T <sub>A</sub> =25°C			110		
		V <sub>IN</sub> =1.2V, V <sub>EN</sub> =high, I <sub>OUT</sub> =200mA		222			
Rois	Output discharge	V=3 3\/ \/= 0\\ T.=25°C	AW3512		276	300	
INDIS	resistance	V <sub>IN</sub> =3.3V, V <sub>EN</sub> =low, T <sub>A</sub> =25°C AW35122		50	75	100	Ω
<b>t</b> R	Output rise time	$V_{IN}$ =3.6 $V$ , $C_{OUT}$ =1 $\mu$ F, $R_{OUT}$ =30 $\Omega$			165		μS
t⊧	Output fall time	V <sub>IN</sub> =3.6V, C <sub>OUT</sub> =1μF, R <sub>OUT</sub> =30Ω	AW3512		60		116
LF.	Output fail tillle	VIN-3.0 V, Cou1=1μΓ, Rou1=30Ω		42		μS	



PA	RAMETER	TEST CONDITION			TYP	MAX	UNIT
ton	Switch turn on time	V <sub>IN</sub> =3.6V, C <sub>OUT</sub> =1μF, R <sub>OUT</sub> =30Ω			238		μS
<b>+</b>	Switch turn off	V <sub>IN</sub> =3.6V, C <sub>OUT</sub> =1μF,	AW3512		17		
toff	time	R <sub>OUT</sub> =30Ω	AW35122		12		μS
ten	Enable time	$V_{IN}$ =3.6V, $C_{OUT}$ =1 $\mu$ F, $R_{OUT}$ =30 $\Omega$		130		μs	
V <sub>IH</sub>	EN input high threshold level			1.2			V
VIL	EN input low threshold level				0.5	V	

### **TIMING DIAGRAM**

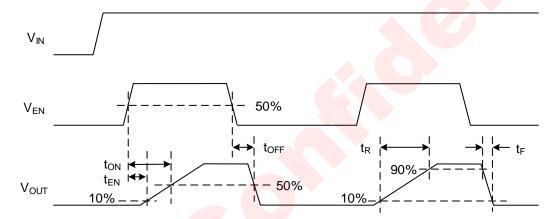
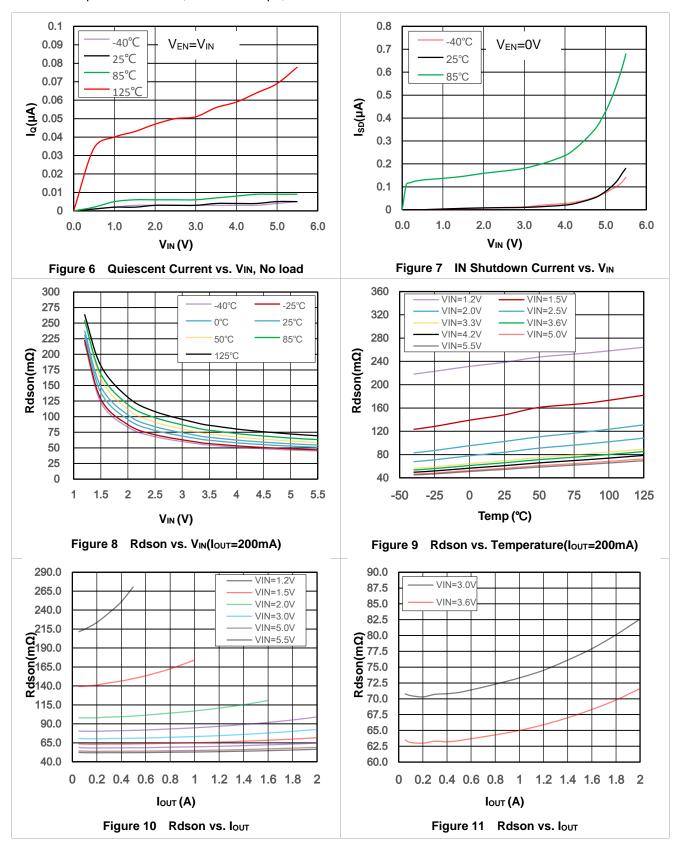


Figure 5 AW3512/AW35122 Timing Diagram

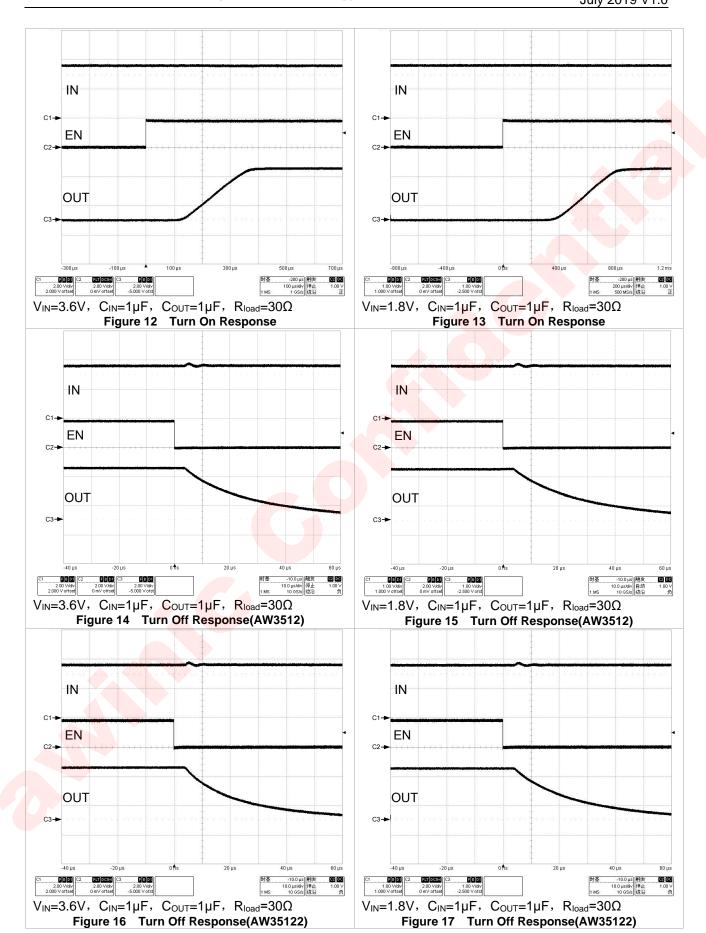


### **TYPICAL CHARACTERISTICS**

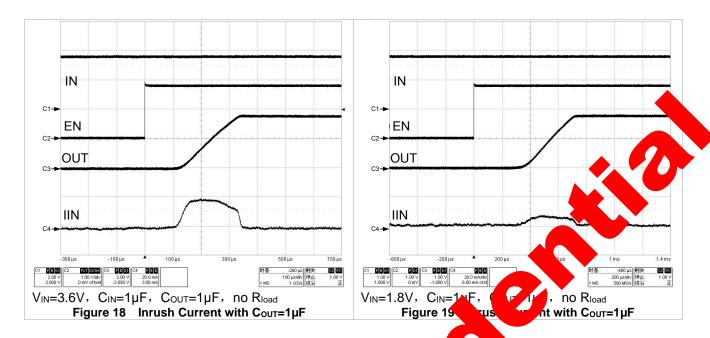
Ambient temperature is 25°C,  $C_{IN} = C_{OUT} = 1\mu F$ , unless otherwise noted.













### **DETAILED FUNCTIONAL DESCRIPTION**

The AW3512/AW35122 integrates a high side P channel MOSFET load switch, and provides a low on-resistance for a low voltage drop across the device. A controlled slew rate is used in applications to limit the inrush current. The part can be turned on, with a supply voltage from 1.2V to 5.5V.

### **TURN ON/OFF CONTROL**

Enable pin is an active high. The device is opened when EN pin is tied low (disable) or pulled down by internal  $7.1M\Omega$  resistor(AW35122), forcing PMOS switch off. The IN/OUT path is activated with a minimum of Vin of 1.2V and EN forced to high level.

**Table 1. Functional Table** 

EN	IN to OUT	OUT to GND		
Low	OFF	ON		
High	ON	OFF		

### **SLEW RATE CONTROL**

When the switch is enabled, the device regulates the gate voltage of MOSFET, and controls the  $V_{OUT}$  slew rate during  $t_R$  to avoid a large input inrush current. The feature reduces the interference to the power supply.

### QUICK OUTPUT DISCHARGE

The AW3512/AW35122 includes the Quick Output Discharge (QOD) feature, in order to discharge the application capacitor connected on OUT pin. When EN pin is set to low level (disable state), a discharge resistance with a typical value of  $276\Omega(AW35122:75\Omega)$  is connected between the output and ground, pull down the output and prevent it from floating when the device is disabled.

### APPLICATION INFORMATION

### POWER SUPPLY RECOMMENDATIONS

The device is designed to operate with a V<sub>IN</sub> range of 1.2V to 5.5V. This supply must be well regulated and placed as close to the device terminals as possible. It must also be able to withstand all transient and load currents, using a recommended input capacitance of 1µF if necessary. If the supply is located more than a few inches from the device terminals, additional bulk capacitance may be required in addition to the ceramic bypass capacitors. If additional bulk capacitance is required, an electrolytic, tantalum, or ceramic capacitor of 10µF may be sufficient.

### MANAGING INRUSH CURRENT

When the switch is enabled, the output capacitors must be charged up from 0V to V<sub>IN</sub>. A input inrush current will appear. The Inrush current can be calculated using Equation 1:

$$Iinrush = Cout \frac{dVout}{dt}$$
 (1)

where:

- C<sub>OUT</sub> = Output capacitance
- Dvout = Output voltage, equals to VIN
- dt = Rise time t<sub>R</sub>.

The AW3512/AW35122 offers a controlled slew rate for minimizing inrush current.

### POWER DISSIPATION

The power dissipation produced by the power MOSFET Rdson in ON-state can be calculated with the following equation:

$$P_D = Rdson \times (I_{OUT})^2$$
 (2)

Where:

- P<sub>D</sub> = Power dissipation (W)
- Rdson = Power MOSFET on resistance (Ω)
- lout = Output current (A)

### THERMAL CONSIDERATIONS

Main contributor in term of junction temperature T<sub>J</sub>(max) is the power dissipation, and T<sub>J</sub>(max) should be restricted to 125°C under ON-state. Junction temperature is directly proportional to power dissipation in the device, it can be calculated by the following equation:

$$T_{J} = T_{A} + R_{\theta J A} \times P_{D} \tag{3}$$

where:

- T<sub>J</sub> = Junction temperature of the device
- T<sub>A</sub> = Ambient temperature
- PD = Power dissipation of the device
- Reja = Junction to ambient thermal resistance. This parameter is highly dependent on board layout.

### **PCB LAYOUT CONSIDERATION**

AW3512/AW35122 is a low ON-Resistance load switch, to obtain the optimal performance, PCB layout should be considered carefully. Here are some guidelines:

- 1. All the peripherals should be placed as close to the device as possible. Place the input capacitor  $C_{\text{IN}}$  on the top layer (same layer as the AW3512/AW35122) and close to IN pin, and place the output capacitor  $C_{\text{OUT}}$  on the top layer (same layer as the AW3512/AW35122) and close to OUT pin.
- 2. The AW3512/AW35122 integrate an up to 1.5A rated PMOS FET, and the PCB design rules must be respected to properly evacuate the heat out of the silicon. By increasing PCB area, especially around IN and OUT pins, the  $R\theta_{JA}$  of the package can be decreased, allowing higher power dissipation. Red bold paths on Figure 18 are power lines that will flow large current, please route them on PCB as straight, wide and short as possible.
- 3. Use rounded corners on the power trace from the power supply connector to AW3512/AW35122 to decrease EMI coupling.

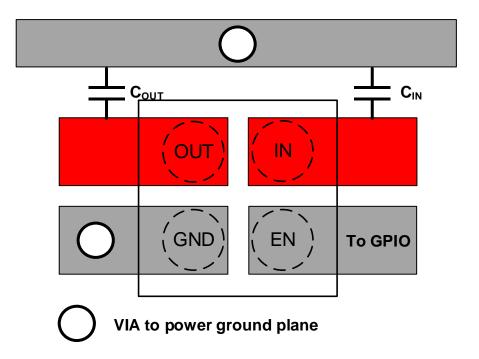
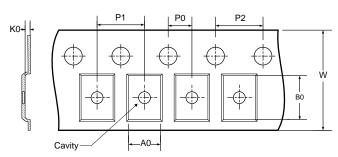


Figure 20 PCB layout example

### TAPE AND REEL INFORMATION

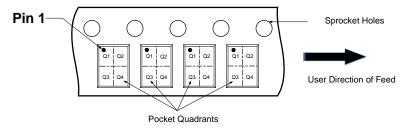
# REEL DIMENSIONS D1 D0

### TAPE DIMENSIONS



- A0: Dimension designed to accommodate the component width
- B0: Dimension designed to accommodate the component length
- K0: Dimension designed to accommodate the component thickness
- W: Overall width of the carrier tape
- P0: Pitch between successive cavity centers and sprocket hole
- P1: Pitch between successive cavity centers
- P2: Pitch between sprocket hole
- D1: Reel Diameter
- D0: Reel Width

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

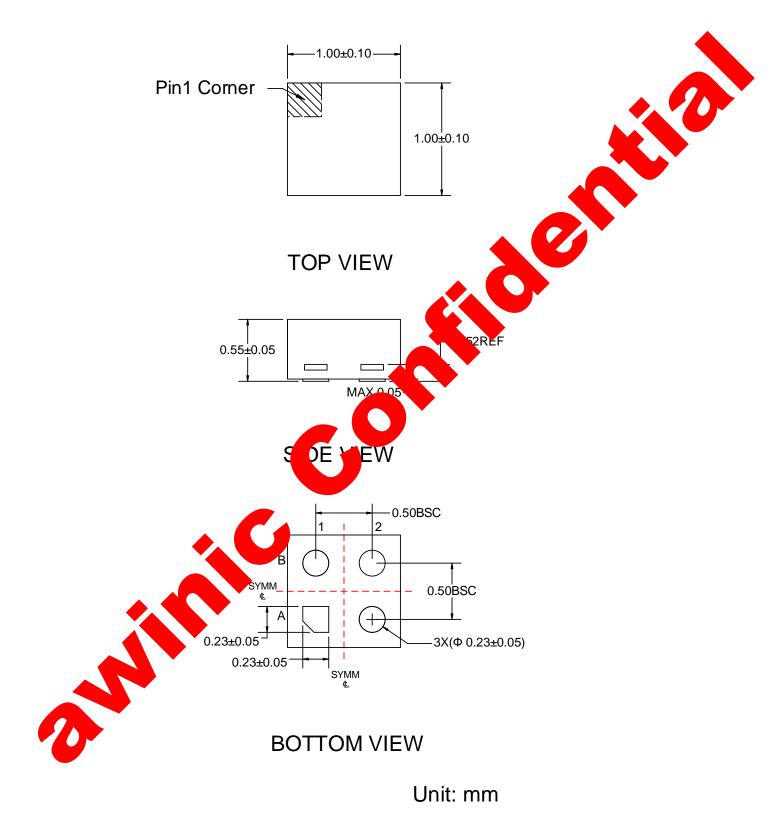


### **DIMENSIONS AND PIN1 ORIENTATION**

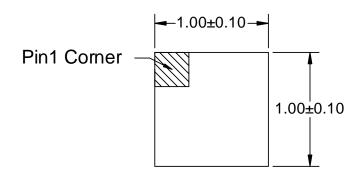
Ī	D1	D0	A0	B0	K0	P0	P1	P2	W	Pin1 Quadrant
	(mm)	Pin i Quadrant								
	178	8.4	1.16	1.16	0.74	2	2	4	8	Q1

All dimensions are nominal

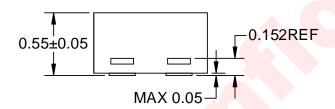
### PACKAGE DESCRIPTION



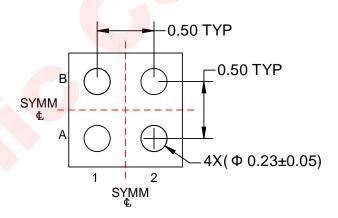
AW3512FDR PACKAGE DESCRIPTION



**TOP VIEW** 



### SIDE VIEW



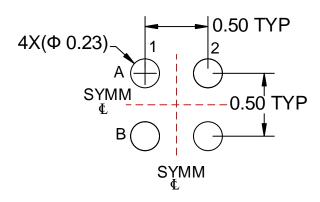
**BOTTOM VIEW** 

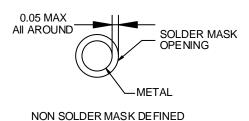
Unit: mm

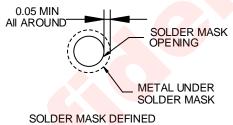
# AW35122FDR PACKAGE DESCRIPTION



### **LAND PATTERN DATA**





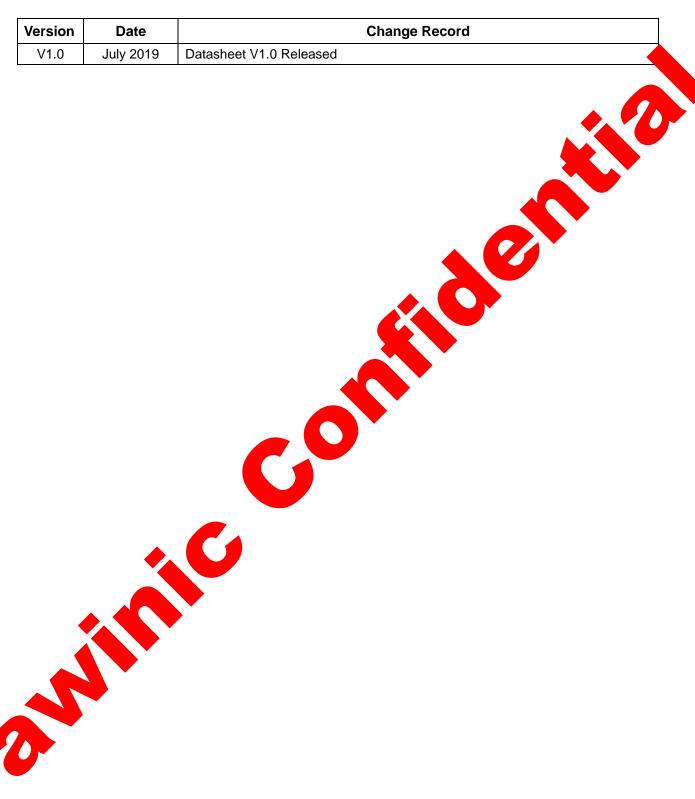


Unit: mm



### **REVISION HISTORY**

Version	Date	Change Record
V1.0	July 2019	Datasheet V1.0 Released





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